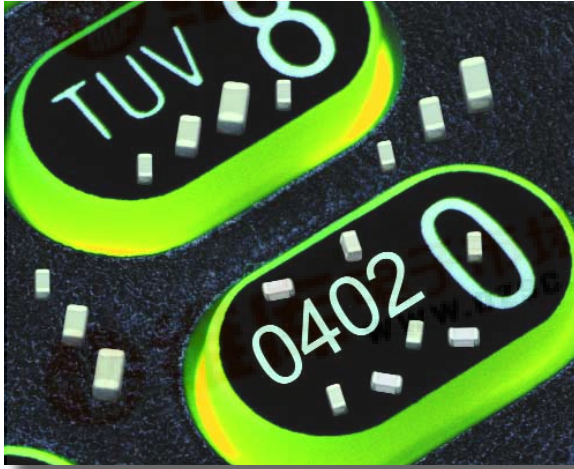


C-SERIES HIGH FREQUENCY CHIP CAPACITORS

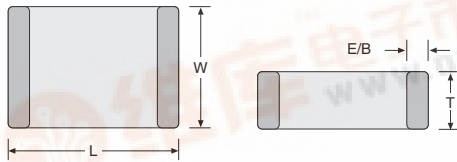


KEY FEATURES

- High-Q / Low ESR
- Self Resonant Frequencies to 23.0 GHz
- Lead-Free Terminations
- Free MLCSoft® for SPICE & S-Parameter Modeling Data

APPLICATIONS

- Cellular Products
- Cable Components
- RF Transceivers
- Wireless LAN
- RF Integrated Circuits
- Custom Applications



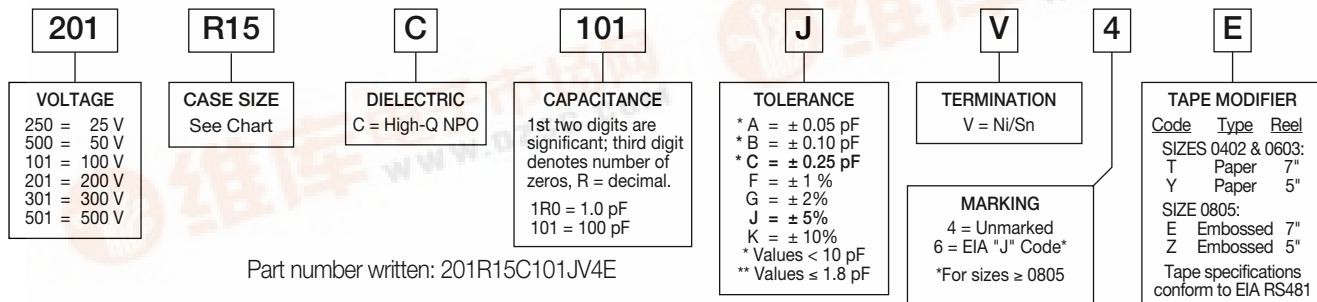
Dielectric RF Performance

S Series	BEST
C Series	BETTER
L Series	GOOD
NPO	?

MECHANICAL CHARACTERISTICS

	R07/ 0402		R14 / 0603		R15 / 0805		S41 / 1210	
	Inches	(mm)	Inches	(mm)	Inches	(mm)	Inches	(mm)
L	.040 ±.004	(1.02 ±0.1)	.062 ±.006	(1.57 ±.15)	.080 ±.008	(2.03 ±.20)	.125 ±.010	(3.18 ±.25)
W	.020 ±.004	(0.51 ±0.1)	.032 ±.006	(0.81 ±.15)	.050 ±.008	(1.27 ±.20)	.095 ±.010	(2.41 ±.25)
T	.020 ±.004	(0.51 ±0.1)	.030 ^{+.005} _{-.003}	(0.76 ^{+.13} _{-.08})	.040 ±.006	(1.02 ±.15)	.060 Max	(1.52)
E/B	.010 ±.006	(0.25 ±.15)	.014 ±.006	(0.35 ±.15)	.020 ±.010	(0.50 ±.25)	.020 ±.010	(0.50 ±.25)

HOW TO ORDER



AVAILABLE CAPACITANCE SELECTION

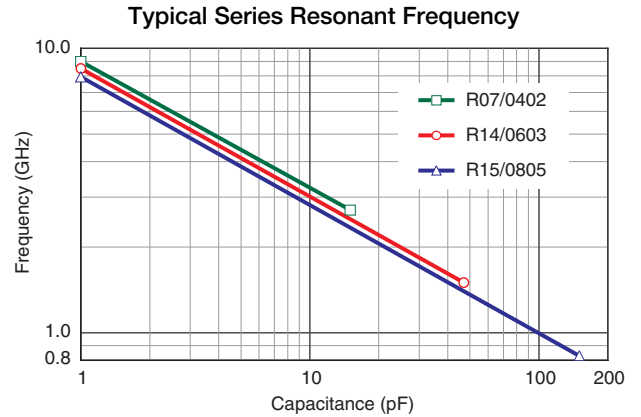
	R07 / 0402	R14 / 0603	R15 / 0805		S41 / 1210
0.2 pF	25 V	200 V			500 V
0.3 pF	25 V	200 V			500 V
0.4 pF	25 V	200 V			500 V
0.5 pF	25 V	200 V	200 V		500 V
0.6 pF	25 V	200 V	200 V		500 V
0.7 pF	25 V	200 V	200 V		500 V
0.8 pF	25 V	200 V	200 V		500 V
0.9 pF	25 V	200 V	200 V		500 V
1.0 pF	25 V	200 V	200 V		500 V
1.1 pF	25 V	200 V	200 V		500 V
1.2 pF	25 V	200 V	200 V		500 V
1.3 pF	25 V	200 V	200 V		500 V
1.5 pF	25 V	200 V	200 V		500 V
1.6 pF	25 V	200 V	200 V		500 V
1.8 pF	25 V	200 V	200 V		500 V
2.0 pF	25 V	200 V	200 V		500 V
2.2 pF	25 V	200 V	200 V		500 V
2.4 pF	25 V	200 V	200 V		500 V
2.7 pF	25 V	200 V	200 V		500 V
3.0 pF	25 V	200 V	200 V		500 V
3.3 pF	25 V	200 V	200 V		500 V
3.6 pF	25 V	200 V	200 V		500 V
3.9 pF	25 V	200 V	200 V		500 V
4.3 pF	25 V	200 V	200 V		500 V
4.7 pF	25 V	200 V	200 V		500 V
5.1 pF	25 V	200 V	200 V		500 V
5.6 pF	25 V	200 V	200 V		500 V
6.2 pF	25 V	200 V	200 V		500 V
6.8 pF	25 V	200 V	200 V		500 V
7.5 pF	25 V	200 V	200 V		500 V
8.2 pF	25 V	200 V	200 V		500 V
9.1 pF	25 V	200 V	200 V		500 V
10 pF	25 V	200 V	200 V		500 V
11 pF	25 V	200 V	200 V		500 V
12 pF	25 V	200 V	200 V		500 V
13 pF	25 V	200 V	200 V		500 V
15 pF	25 V	200 V	200 V		500 V
16 pF		200 V	200 V		500 V
18 pF		200 V	200 V		500 V
20 pF		100 V	200 V		500 V
22 pF		100 V	200 V		500 V
24 pF		100 V	200 V		500 V
27 pF		100 V	200 V		500 V
30 pF		100 V	200 V		500 V
33 pF		100 V	200 V		500 V
36 pF		100 V	200 V		500 V
39 pF		100 V	200 V		500 V
43 pF		100 V	200 V		500 V
47 pF		100 V	200 V		500 V
56 pF			200 V		500 V
68 pF			200 V		500 V
82 pF			200 V		500 V
100 pF			200 V		500 V
120 pF			100 V		300 V
150 pF			100 V		300 V
					180 pF
					220 pF
					270 pF
					330 pF
					390 pF
					470 pF
					560 pF
					680 pF
					820 pF
					1000 pF

This selection chart represents basic C/V capability in this series. Please contact the factory for capacitance, voltage, case size combinations not shown.



DIELECTRIC CHARACTERISTICS

TEMPERATURE COEFFICIENT:	0 ± 30ppm /°C, -55 to 125°C
QUALITY FACTOR:	2,500 min., 10,000 typical
INSULATION RESISTANCE:	>1,000 GΩ @ 25°C, WVDC; 125°C IR is 10% of 25°C rating.
DIELECTRIC STRENGTH:	2.5 X WVDC Min., 25°C, 50 mA max
TEST PARAMETERS:	1MHz ±50kHz, 1.0±0.2 VRMS, 25°C
AVAILABLE CAPACITANCE:	Size 0402: 0.2 - 15 pF Size 0603: 0.2 - 47 pF Size 0805: 0.2 - 150 pF Size 1210: 0.5 - 1000 pF



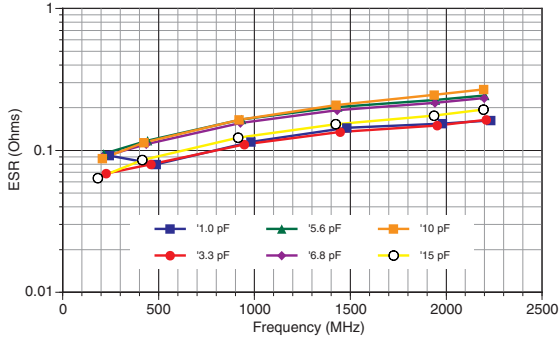
MECHANICAL & ENVIRONMENTAL CHARACTERISTICS

	SPECIFICATION	TEST PARAMETERS
SOLDERABILITY:	Solder coverage ≥ 90% of metalized areas	Preheat chip to 120°-150°C for 60 sec. Dip terminals in rosin flux then dip in 62Sn/36Pb/2Ag solder @ 240±5°C Dip time = 5±1 sec.
RESISTANCE TO SOLDERING HEAT:	Chip should not crack. Solder coverage ≥ 80%	Preheat chip to 120°-150°C for 60 sec. Dip terminals in rosin flux then dip in 62Sn/36Pb/2Ag solder @ 260±5°C Dip time = 10±1 sec.
TERMINAL ADHESION:	Termination should not pull off. Ceramic should remain undamaged.	Linear pull force exerted on axial leads soldered to each terminal. Terminal strength: For 0402: ≥2.0Lbs For 0603: ≥2.0Lbs For 0805: ≥5.0Lbs
PCB DEFLECTION:	No mechanical damage. Cap. change: 2% or .5pF Max	Glass Epoxy PCB: 1 mm deflection
LIFE TEST:	Cap. change: 2% or .5pF Max I.R. = Initial value	1000 Hours, 125°C, 200% rated voltage
THERMAL SHOCK:	Cap. change: 2% or .5pF Max I.R. = 70% of initial value	5 CYCLES: 30±3 minutes @ -55°C, 3 min. @ 25°C 30±3 min. @ +125°C, 3 min. @ 25°C
MOISTURE RESISTANCE:	Cap. change: 2% or .5pF Max I.R. = 70% of initial value	240 Hours, 85% Relative Humidity, 85°C, 1.5 VDC

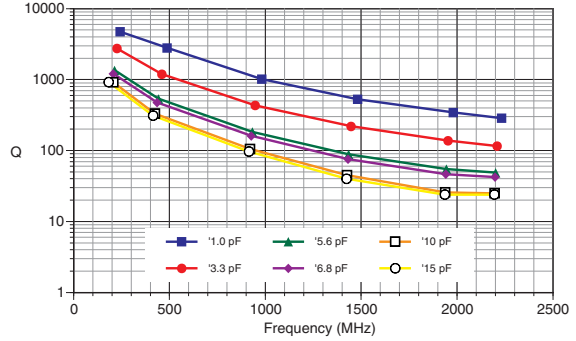


RF CHARACTERISTICS VERSUS FREQUENCY

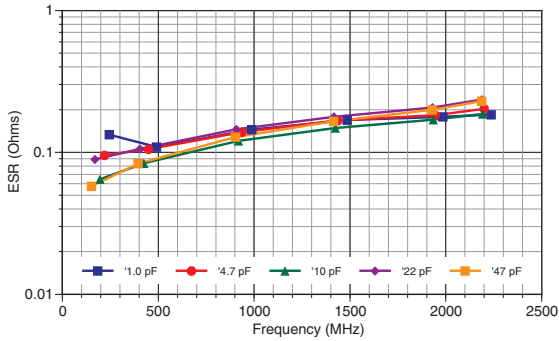
Equivalent Series Resistance: 0402/R07C



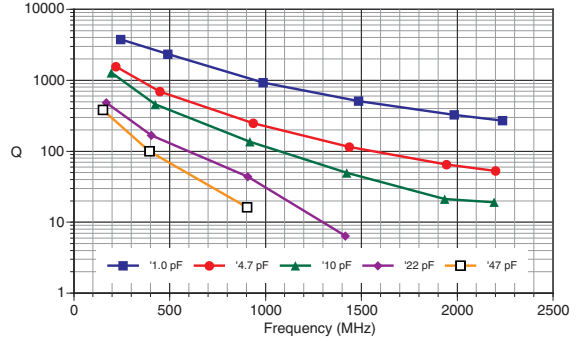
Q Factor: 0402/R07C



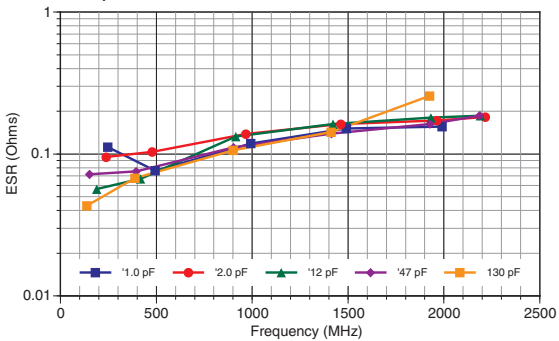
Equivalent Series Resistance: 0603/R14C



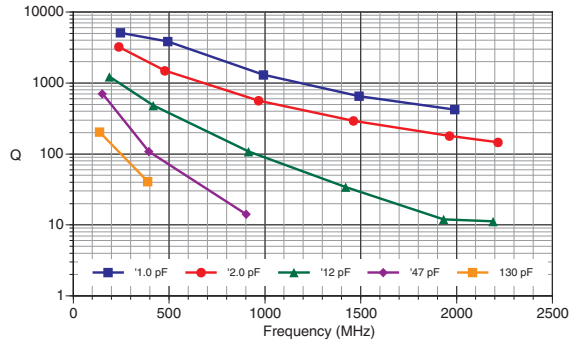
Q Factor: 0603/R14C



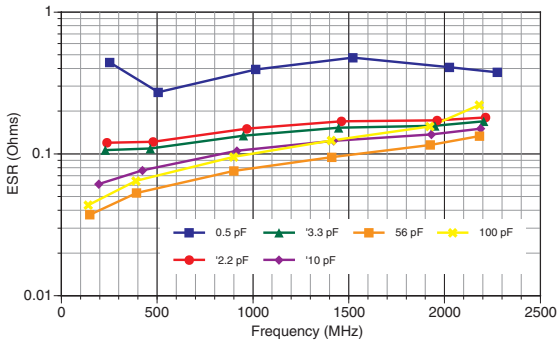
Equivalent Series Resistance: 0805/R15C



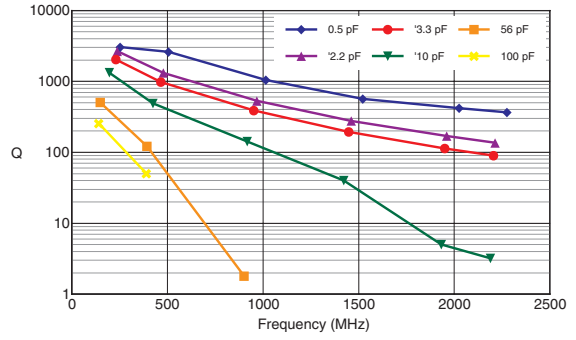
Q Factor: 0805/R15C



Equivalent Series Resistance: 1210/S41C



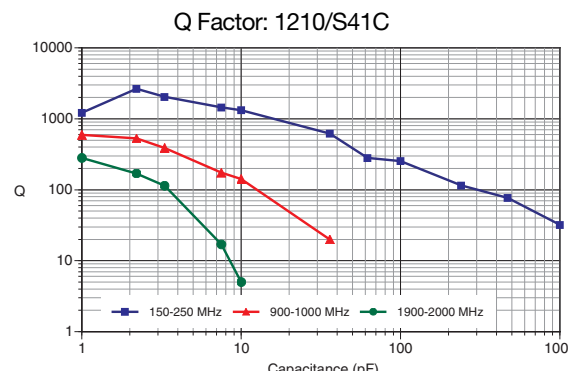
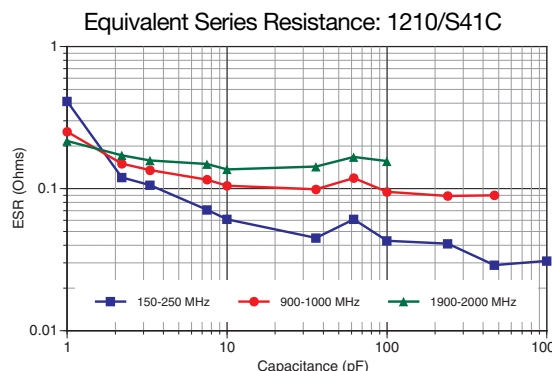
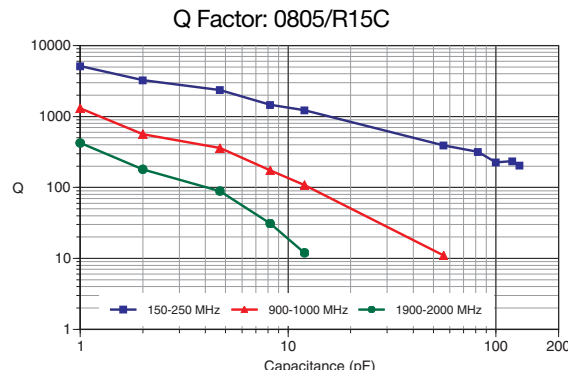
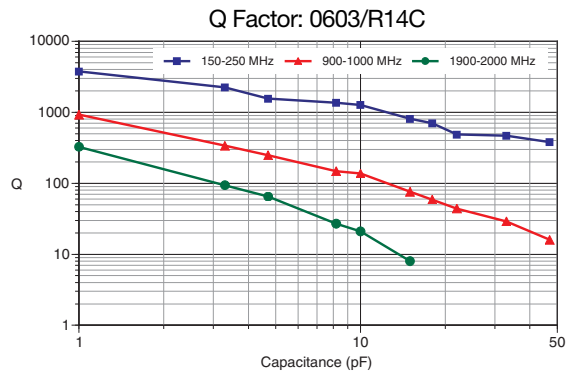
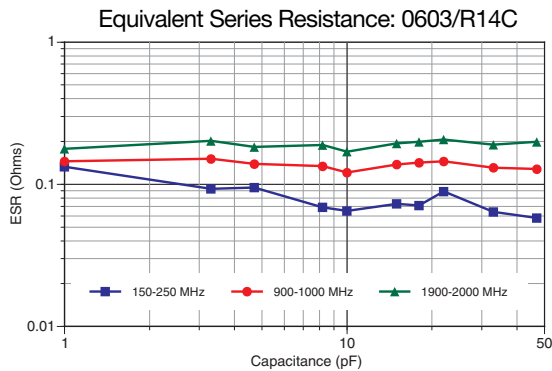
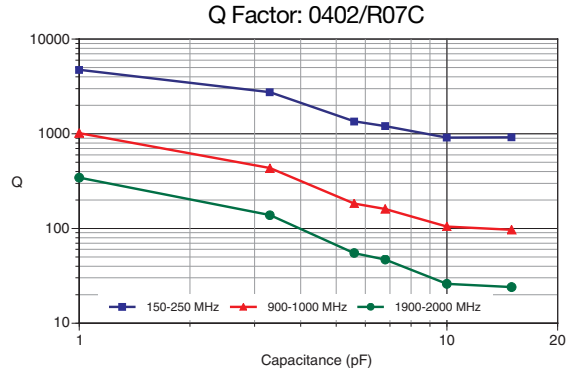
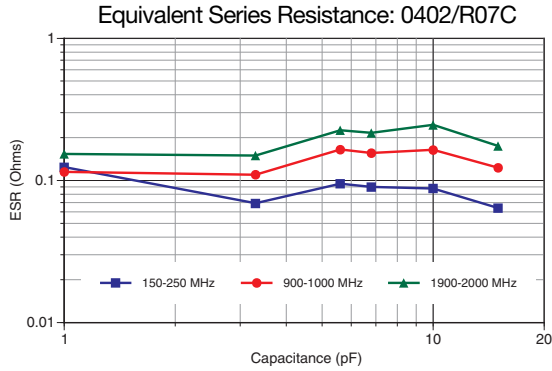
Q Factor: 1210/S41C



Measurements performed on a Boonton 34A Resonant Coaxial Line and represent typical capacitor performance.



RF CHARACTERISTICS VERSUS CAPACITANCE



Measurements performed on a Boonton 34A Resonant Coaxial Line and represent typical capacitor performance.

